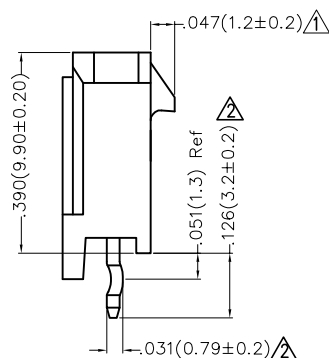
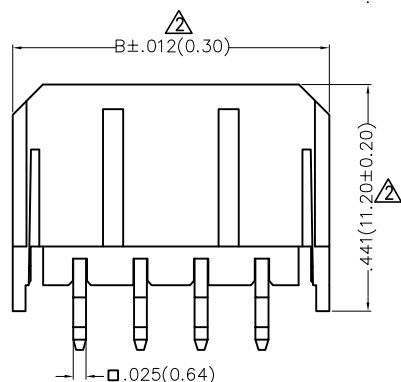
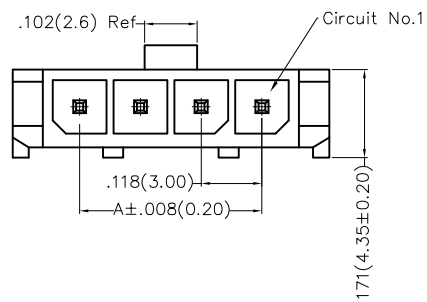


Recommended P.C.Board Layout
General tolerances: $\pm 0.002(0.05)$

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1		Dimensions change	18/MAR/20	KATE	CHERRY
2		1:Update Dimensions 2:Update Material 3:Add Circuit Size Layout	13/AUG/24	MATT	LEO

Electrical

Current Rating: 5.0A AC(rms)/DC
Voltage Rating: 250V AC(rms)/DC
Contact Resistance: 10 mΩ Max
Insulation Resistance: 1000 MΩ MIN
Withstanding Voltage: 1500V AC r.m.s
Temperature Range—Operating: $-40^{\circ}\text{C} \sim +105^{\circ}\text{C}$

Material and Plating

Housing: PA6T(UL 94V-0)
Contact Pin: Brass
Plating: Tin Plated
Mates With: FHG30002 Series

Circuits (n)	Part No.	Dimensions(in/mm)	
		A	B
2	FWF30004-S02S22K6B	.118(3.00)	.380(9.65)
3	FWF30004-S03S22K6B	.236(6.00)	.498(12.65)
4	FWF30004-S04S22K6B	.354(9.00)	.616(15.65)
5	FWF30004-S05S22K6B	.472(12.00)	.734(18.65)
6	FWF30004-S06S22K6B	.591(15.00)	.852(21.65)
7	FWF30004-S07S22K6B	.709(18.00)	.970(24.65)
8	FWF30004-S08S22K6B	.827(21.00)	1.089(27.65)
9	FWF30004-S09S22K6B	.945(24.00)	1.207(30.65)
10	FWF30004-S10S22K6B	1.063(27.00)	1.325(33.65)
11	FWF30004-S11S22K6B	1.181(30.00)	1.443(36.65)
12	FWF30004-S12S22K6B	1.299(33.00)	1.561(39.65)

Ordering Information

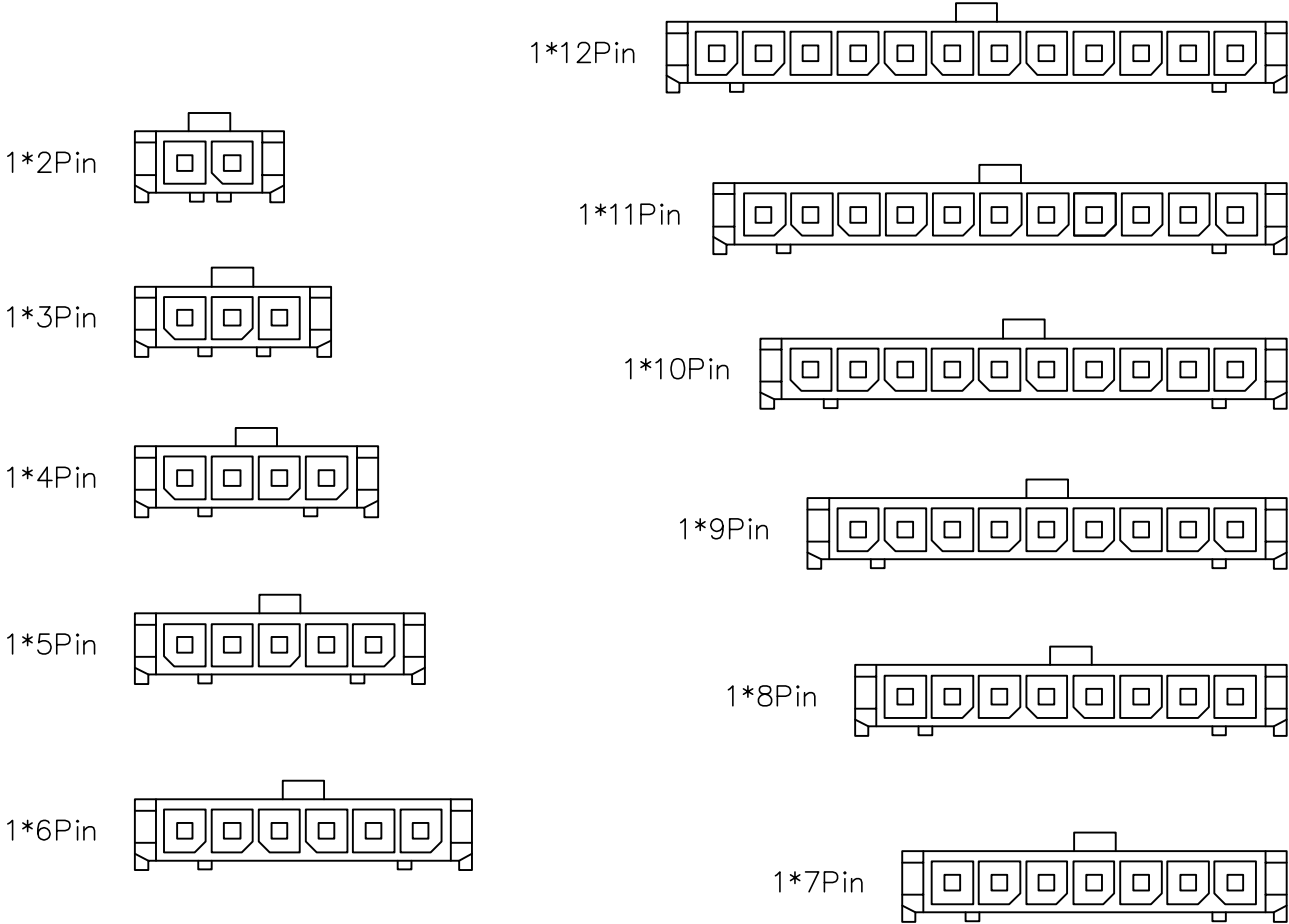
FWF 300 04 — S XX S 2 2 K6 B
1 2 3 4 5 6 7 8 9 10

1 Category FWF—Wafer	2 Series Number 300—Pitch 3.0mm	3 Distinction No. 04	4 Row Option S—Single Row	5 Circuits XX	6 Entry Angle S—180° Vertical
7 Plating 2—Tin Plated	8 Material—Resin 2—PA6T	9 Color—Resin K6—Black	10 Packaging B—PE Bag		

 THIRD ANGLE PROJECTION		GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 01/JUL/13	PART NO. FWF30004-SXXS22K6B	ITEM NO. FWF30004	 Building Technology Cornerstone	
		X.±.012(0.30)	X.±5°	CHECKED BY	DATE	TITLE Wire to Board (Wafer) Pitch 3.0mm 180° Vertical (DIP)			
DESIGN UNITS Inch (metric)		X.X±.008(0.20)	X.±2°	CHERRY	01/JUL/13				REV 2
		X.XX±.006(0.15)	.XX°±1°	DRAWN BY	DATE				
SCALE 5:1	SIZE A4	X.XXX±.004(0.10)	.XXX±0.5°	JACOB	01/JUL/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

Circuit Size Layout



 THIRD ANGLE PROJECTION		GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 01/JUL/13	PART NO. FWF30004-SXXS22K6B	ITEM NO. FWF30004	 Building Technology Cornerstone	
		X.±.012(0.30)	X.±5°	CHECKED BY CHERRY	DATE 01/JUL/13	TITLE Wire to Board (Wafer) Pitch 3.0mm 180° Vertical (DIP)			
DESIGN UNITS Inch (metric)		X.X±.008(0.20)	X.±2°	DRAWN BY JACOB	DATE 01/JUL/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		X.XX±.006(0.15)	.XX'±1°						
SCALE 5:1	SIZE A4	X.XXX±.004(0.10)				REV 2			
		.XXX±0.5°				SHEET NO. 2/2			